

Emulated EEPROM Quick Start Guide

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1 Introduction

1.1 Emulated EEPROM

Some families of the S12X series of microcontrollers (MCUs), such as the MC9S12XEP100, have an enhanced region labeled as EEPROM in the memory map. This region does not contain conventional EEPROM, but has flash and RAM components that can be managed by the enhanced flash module (FTM) in a unique manner, allowing the emulation of EEPROM. Because the FTM allows the partitioning of EEPROM resources to suit an application, a significant degree of memory flexibility becomes available to users.

1.2 Objective

The objective of this application note is to accelerate the introduction of emulated EEPROM (EEE). In particular, it is suited to individuals familiar with programming and the use of a debugger but who have little or no experience

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S12XE EEE in the S12X Memory Map

with EEE. This document seeks to teach users through a simple EEE example. Most low-level details are put aside so as to allow focus on higher-level concepts associated with the EEE. Users will need a programming board with an S12XE MCU and a debugger to single-step through the example code and run through portions of that code. This document shows:

- Where the EEE components exist in the memory map
- Examples of three configurations
- The FTM command flow
- How data behaves in the buffer RAM in different configurations

Other important topics are also discussed. For more details on EEE, refer to Freescale application note AN3490, “Overview of the MC9S12XE Emulated EEPROM,” available at www.freescale.com.

2 S12XE EEE in the S12X Memory Map

Figure 1 shows how this enhanced EEPROM region fits into the S12XE local and global memory map. The figure also reveals the enhanced EEPROM components of data flash and buffer RAM.

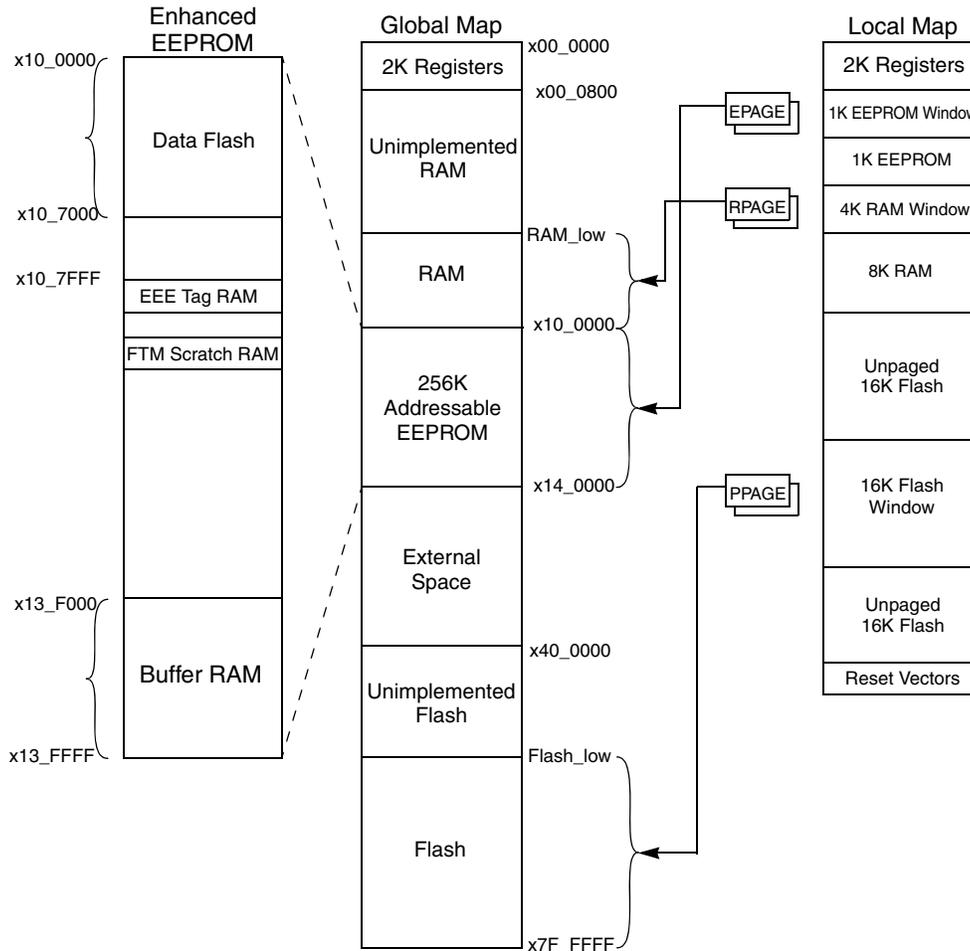


Figure 1. EEPROM Region in the S12XE Memory Map

3 Configurations of the Enhanced EEPROM Region

Because of the enhancement of the FTM, these EEE components can be used in three general configurations described below:

As Data Flash and Buffer RAM: All sections of buffer RAM and sectors of data flash are used as conventional RAM and flash. No partitions of EEE are created, and EEPROM emulation is disabled.

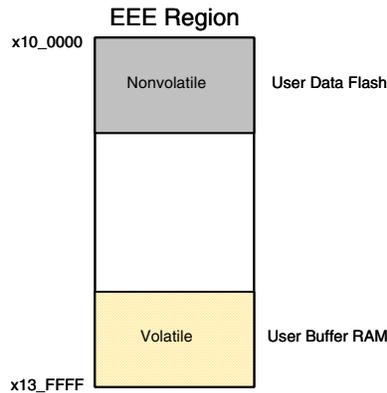


Figure 2. EEPROM Region Configured as Data Flash and Buffer RAM

As EEE: All of the EEE resources are fully partitioned as EEE. This results in all buffer RAM being used as EEE RAM, and all data flash used as EEE flash. Once EEE is enabled, this allows the FTM to take volatile data written into the EEE RAM and store records of this data in EEE flash. The FTM can automatically manage these records without user intervention. After the next MCU reset, the FTM will stall the central processing unit (CPU) from executing instructions until data from the records in EEE flash has been copied back to EEE RAM. This management of data allows the EEE RAM to be perceived as EEPROM, except that users can modify data in this section at any time.

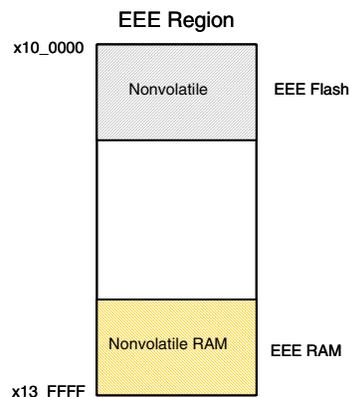


Figure 3. Configured as EEE

As EEE, Data Flash, and Buffer RAM: This is a mixed configuration. Portions of the buffer RAM and the data flash are partitioned as EEE RAM and EEE flash, respectively. The remaining sections and sectors still exist as buffer RAM and data flash and may be used as desired. Data placed in EEE RAM will be managed by the FTM to support EEE.

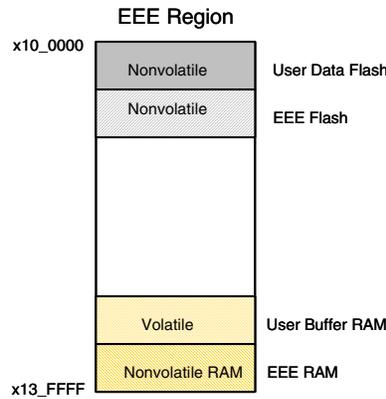


Figure 4. Configured as EEE, Data Flash, and Buffer RAM

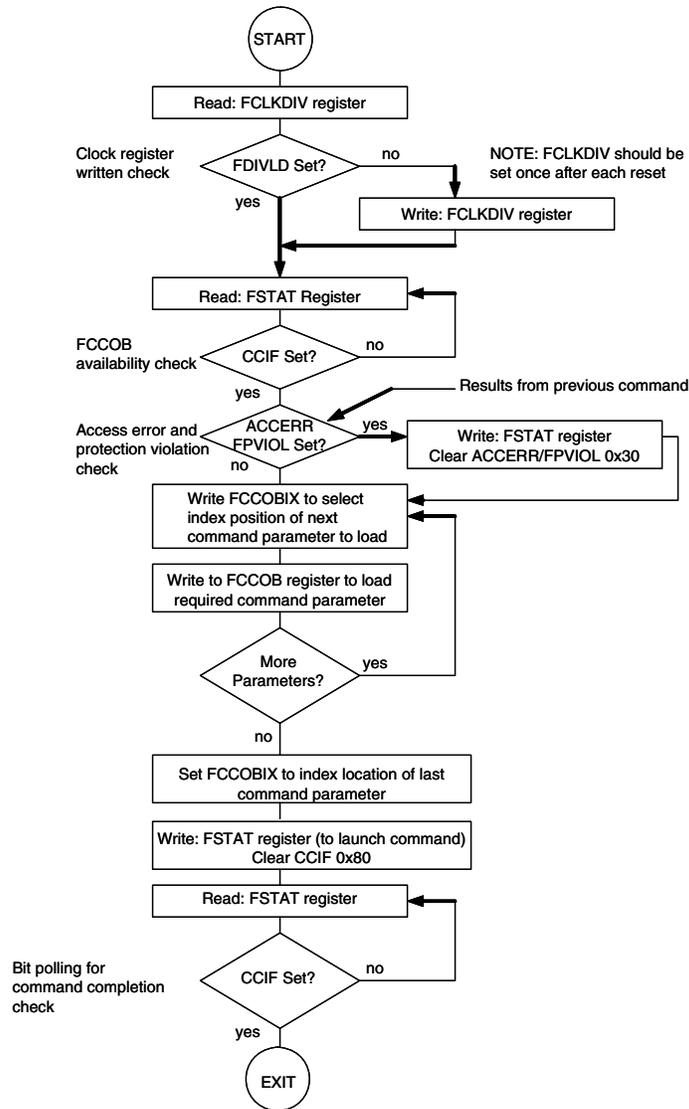
3.1 Launching FTM Commands

In order to write, read, or configure the memory regions associated with the FTM, commands must be loaded into the FTM and executed. The process involves a specific sequence that is used to set the FTM command parameters and launch execution. The following portion of code illustrates an example of instructions within a function, “LaunchFlashCommand,” used to set up and execute FTM commands. Users should follow a defined flow to reduce the risk of module errors. [Figure 5](#) shows the recommended FTM command execution flow.

```

FSTAT = 0x30; //Use store instruction to clear ACCERR, FPVIOL.
/*****SET UP THE FTM COMMAND AND PARAMETERS*****/
FCCOBIX = 0; //Set CCOB index to 0 to begin command setup.
FCCOBHI = ccob0high; //Write ccob0 high-byte command value.
FCCOBLO = ccob0low; //Write ccob0 low-byte parameter, if used.
if (params > 0) //Continue if more parameters to specify.
{
    FCCOBIX++;
    FCCOB = ccob1; //Write next word parameter to CCOB1 buffer.
    if (params > 1) //Continue if more parameters to specify.
    {
        FCCOBIX++;
        FCCOB = ccob2; //Write next word parameter to CCOB2 buffer.
        if (params > 2) //Continue if more parameters to specify.
        {
            FCCOBIX++;
            FCCOB = ccob3; //Write next word parameter to CCOB3 buffer.
            if (params > 3) //Continue if more parameters to specify.
            {
                FCCOBIX++;
                FCCOB = ccob4; //Write next word parameter to CCOB4 buffer.
                if (params > 4) //Continue if more parameters to specify.
                {
                    FCCOBIX++;
                    FCCOB = ccob5; //Write next word parameter to CCOB5 buffer.
                    if (params > 5) //Continue if more parameters to specify.
                    {
                        FCCOBIX++;
                        FCCOB = ccob6; //Write next word parameter to CCOB6 buffer.
                        if (params > 6) //Continue if more parameters to specify.
                        {
                            FCCOBIX++;
                            FCCOB = ccob7; //Write next word parameter to CCOB7 buffer.
                        }
                    }
                }
            }
        }
    }
}
/*****/
FSTAT = 0x80; //Clear buffer-empty-flag to start FTM command.
while (!FSTAT_CCIF); //Now wait for the FTM command to complete.
status.fstat_var = FSTAT; //Copy FSTAT register state for later comparison.
status.ferfstat_var = FERSTAT; //Copy FERSTAT register state for later comparison.
return(status); //After FTM command completed, return status.

```



Generic Flash Command Write Sequence Flowchart

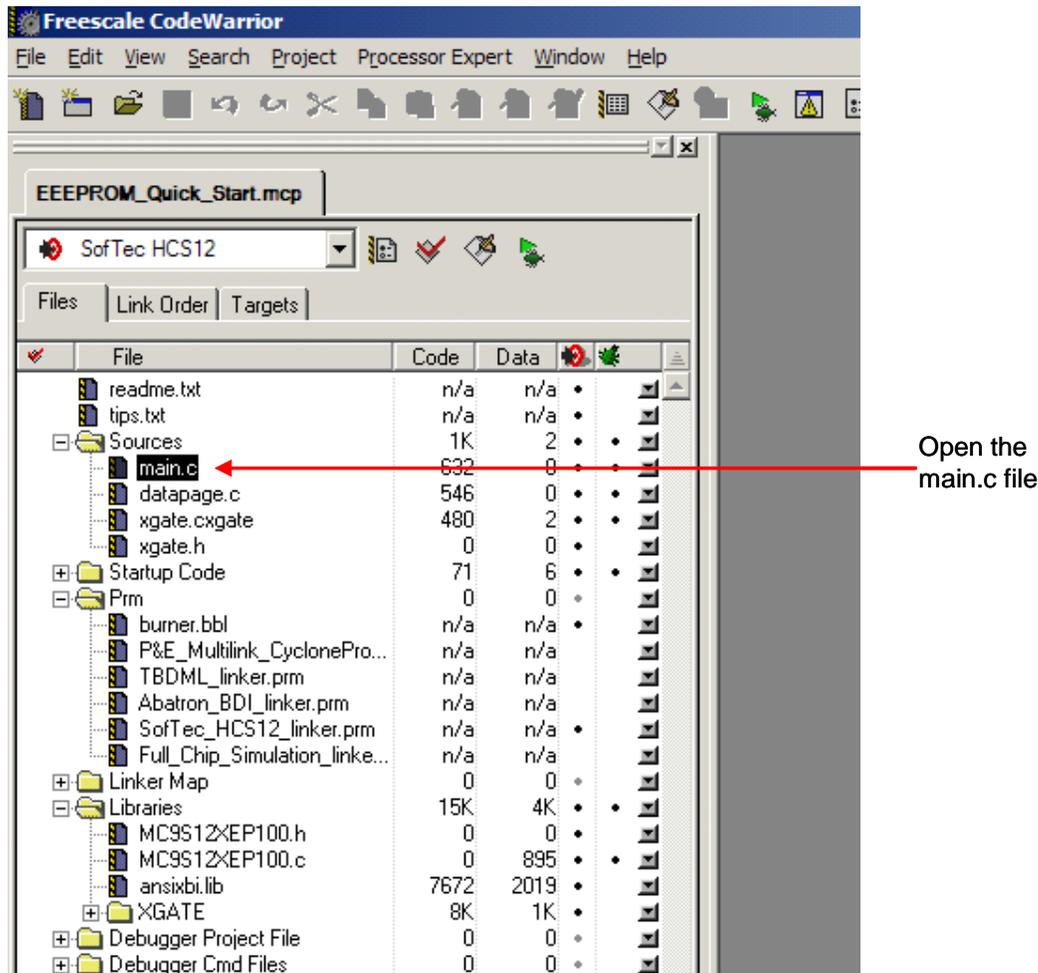
Figure 5. FTM Command Execution Flowchart

3.2 Checking for Errors

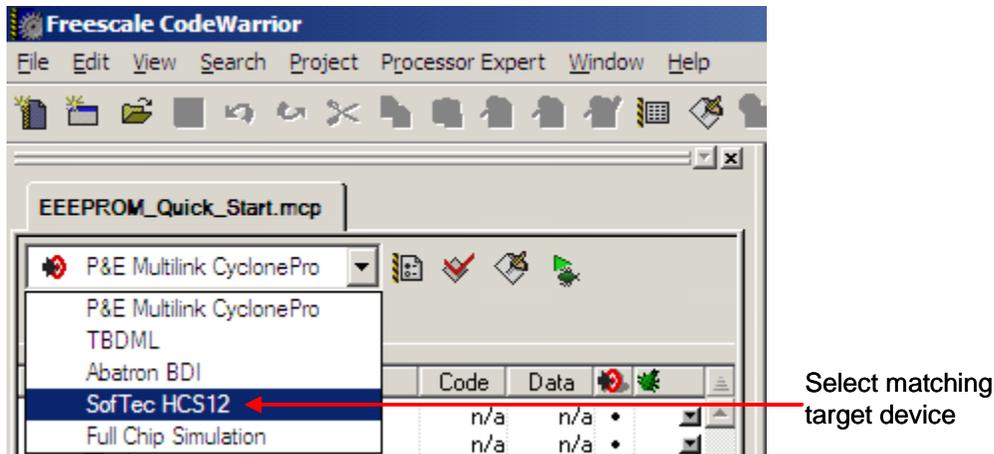
After the completion of each FTM command, indicated by a set CCIF flag, it is important to check both flash status registers. The FSTAT and FERSTAT registers contain error flags that are set whenever a particular error condition is met. If errors are detected, the user should use software to mitigate the occurrence and clear the error flag. When registers such as FSTAT and FERSTAT have multiple bits that can be cleared via a write 1, users should avoid the use of the BSET instruction to clear these bits. This could result in an unintended clear of other flags within the register. If applicable, a STAA instruction or STAB instruction may be more appropriate.

4 EEPROM Quick Start Project Setup

The EEPROM Quick Start project containing the example code for this application note can be downloaded from the Freescale public website. Users without a compiler can also download a free version of CodeWarrior™ for the S12X. To begin setup of the EEPROM Quick Start project, open the “EEPROM_Quick_Start.mcp” project file. Once opened, users should select and open the “main.c” file, which contains the majority of the code referenced in this application note. Comments have been placed throughout the file, along with step numbers that correspond with the discussion in this application note.



Before attempting to compile and load the project, a few important settings must be checked. First, a target should be selected that matches the communication device that the user will use when programming the MCU.



Next, a suitable flash clock divide value (FCLK_DIV) must be defined to ensure that the FTM works properly. In the following clock divide section of “main.c,” the user should ensure that a viable FCLK_DIV value is uncommented, or should define a new divide value that corresponds to the oscillator on the MCU board. A table of suitable values can be found in the S12XE flash block guide. In this example, the code does not engage the clock generator (CRG) module, but runs entirely from an external oscillator.

```
//CLOCK DIVIDE SECTION
//Uncomment the FCLK_DIV value according to the oscillator crystal.
//These values are chosen from the MC9S12XE100 datasheet.
//#define FCLK_DIV 0x1 // Flash clock divider for 2MHz crystal
#define FCLK_DIV 0x3 // Flash clock divider for 4MHz crystal
//#define FCLK_DIV 0x7 // Flash clock divider for 8MHz crystal
//#define FCLK_DIV 0x9 // Flash clock divider for 10MHz crystal
//#define FCLK_DIV 0x18 // Flash clock divider for 26MHz crystal
```

In the following code section, the parameters for partitioning the EEPROM resources are defined. A macro and #define are used to define the size of the EEE before compiling the project. The amount of buffer RAM to be set aside as EEE RAM is specified, as well as the amount of flash to be reserved as data flash. The remaining resources of data flash will be used as EEE flash. Once defined, these parameters are then used later in the FTM command process to fully partition and implement the resources.

Other configurations are possible. The user may adjust these parameters within proper limitations and proper ratio, as explained in application note AN3490.¹

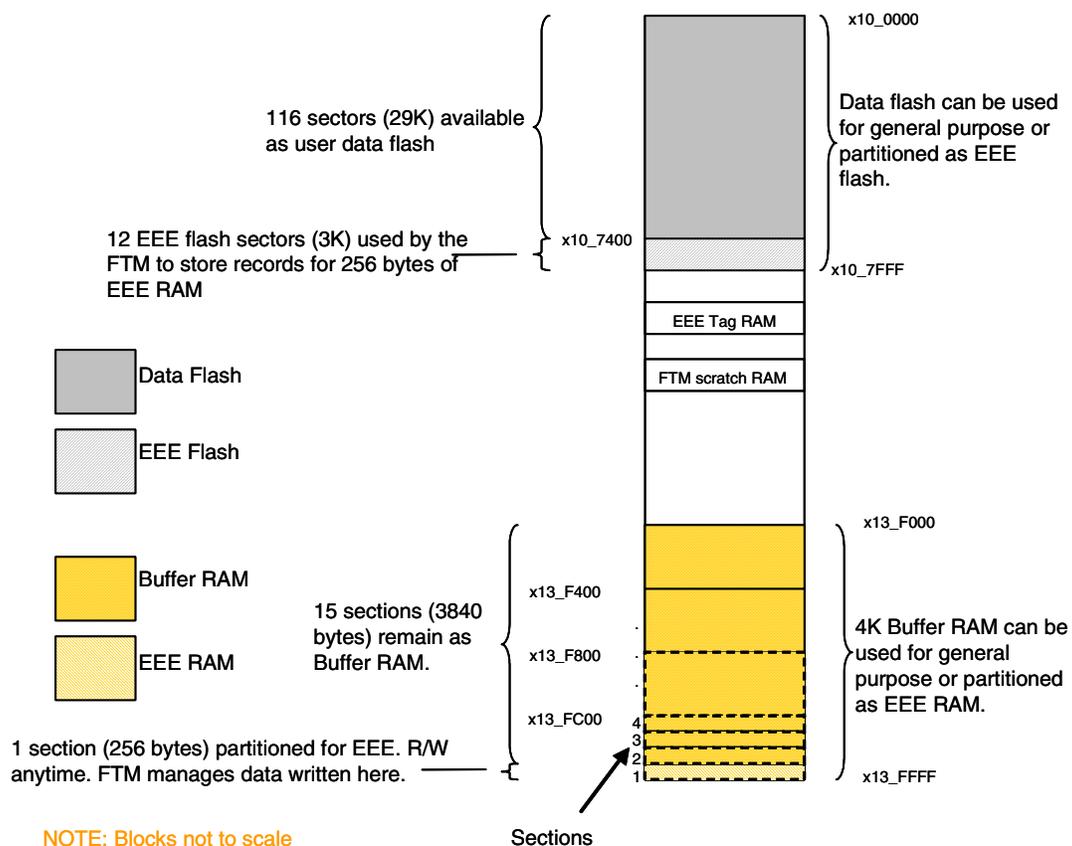
```
//EEE SIZE SECTION
/**** SET THE SIZE OF THE EEE HERE ****/
#define EEE_RAM 1 //Specify the # of EEE RAM sections for the FTM (Flash
//module) to use as EEE. The valid range is 0-16 sections.

/**** CALCULATES AMOUNT OF DATA FLASH FOR GENERAL USE *****/
#if(EEE_RAM == 1)
#define DFPART (128 - 12)
#else
#define DFPART (128 - (8 * EEE_RAM))
```

1. The formula used to calculate the number of sectors of data flash for partitioning uses the minimum ratio of partitioned buffer RAM sections to partitioned data flash sectors. Other ratios are possible. Refer to AN3490 for more details.

```
#endif
```

When the FTM creates a full partition using the parameter values above, the arrangement yields 1 section of EEE RAM and 12 sectors of EEE flash. The remaining sections and sectors exist as buffer RAM and data flash, respectively. Although sectors describe physical divisions that are present within flash, the term “sections” is used here to describe only imaginary divisions of buffer RAM. [Figure 6](#) shows a block diagram of the resulting configuration of the EEPROM region. The figure identifies the buffer RAM sections for clarity. Here, the section numbers are labeled in decreasing order as the buffer RAM address increases. When EEE is enabled, the FTM copies new data written in EEE RAM and stores records of that data in the sectors partitioned as EEE flash.



Example Configuration: 1 EEE RAM Section, 12 EEE Flash Sectors

Figure 6. Example Configuration: 1 EEE RAM Section, 12 EEE

To use the example, compile and load the code into an S12XE MCU. If using CodeWarrior, this should cause the debugger to appear. [Figure 7](#) shows a debugger image capture where a memory window and variables can be used to observe registers and data values in the EEPROM region. More captures and figures follow to highlight important steps within the project.

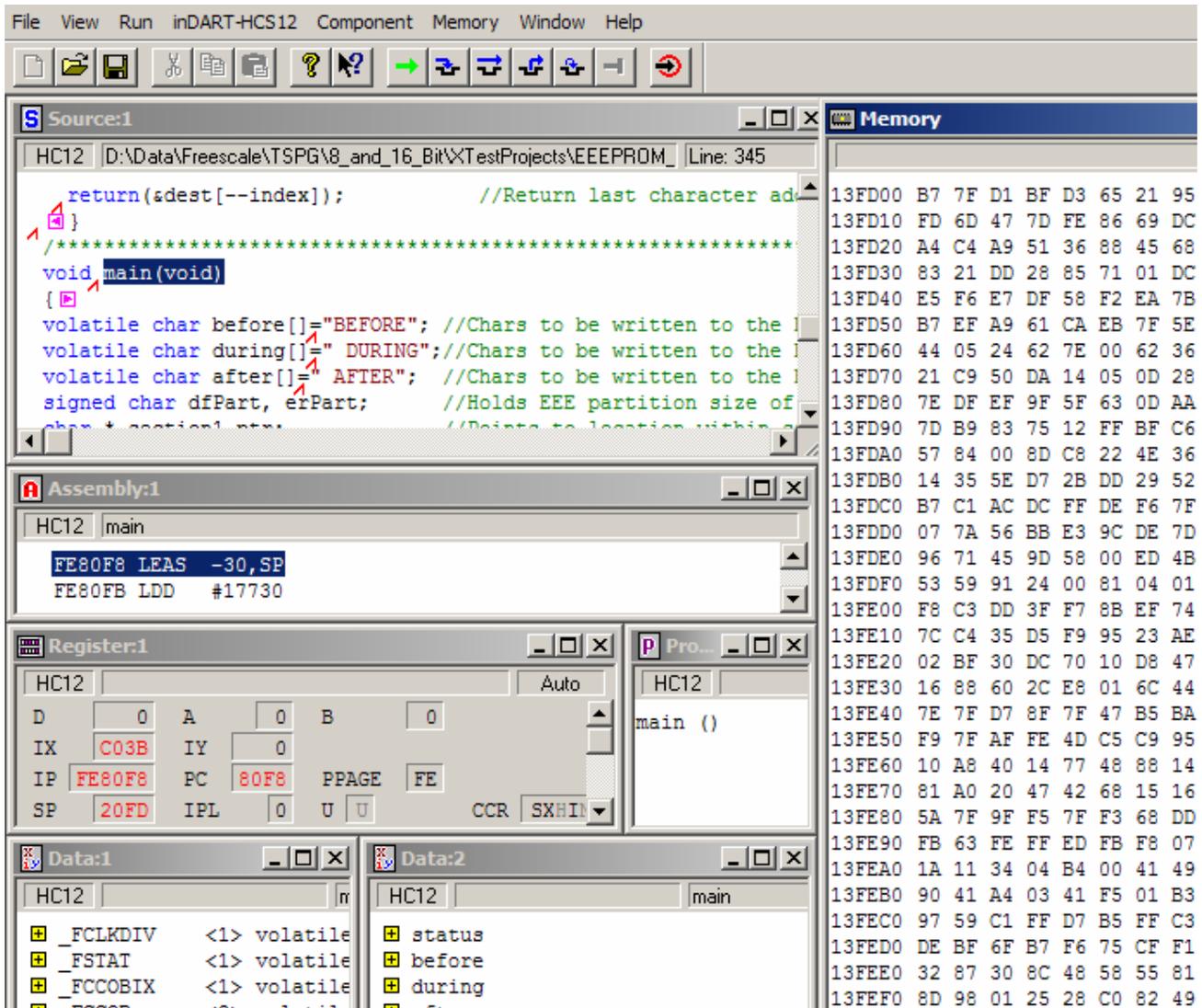
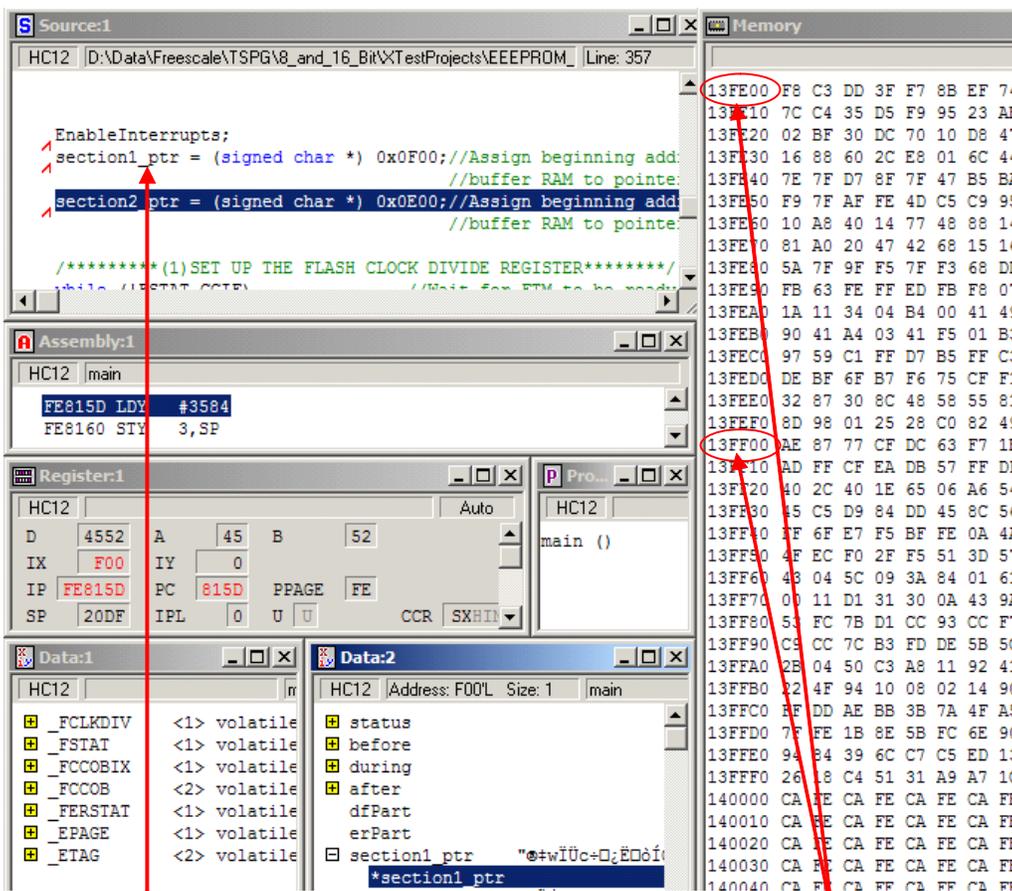


Figure 7. Debugger Example

5 Accessing EEPROM

To read and write within the EEPROM region, pointers can be assigned appropriate address locations. This is done at the beginning of the main function, as shown in the code below and in [Figure 8](#). At different stages of the programming example, text strings will be written into adjacent sections 1 and 2 of EEE RAM and buffer RAM, respectively. In this case, adjacent sections are chosen to make the difference in behavior more apparent in the memory window. As users proceed, the behavior of the text strings should be observed after each example step. This will help users understand the emulated properties of EEE RAM versus general buffer RAM.

```
/* *****/void  
main(void)  
{  
volatile char before[]="BEFORE"; //Chars to be written to the EEE and Buffer RAM  
volatile char during[]=" DURING"; //Chars to be written to the EEE and Buffer RAM  
volatile char after[]=" AFTER"; //Chars to be written to the EEE and Buffer RAM  
signed char dfPart, erPart; //Holds EEE partition size of data Flash and buffer RAM  
char * section1_ptr; //Points to location within section1 of buffer RAM  
char * section2_ptr; //Points to location within section2 of buffer RAM  
volatile ErrType status;  
  
EnableInterrupts;  
section1_ptr = (signed char *) 0x0F00; //Assign beginning address of section1 of  
//EEE RAM to pointer.  
section2_ptr = (signed char *) 0x0E00; //Assign beginning address of section2 of  
//buffer RAM to pointer.
```



pointer assigned beginning of section address in C code

Beginning address of sections 1 and 2.

Figure 8. Assigning Address Locations to Pointers

6 EEE Quick Start Code Steps

The remainder of this application note proceeds through ten steps labeled in the main project function. Each step is followed by a corresponding image capture of the code. Users should use a debugger to execute the code and observe the changes that occur in the debugger memory window. This should help to understand some of the EEE behavior.

1. Assign the previously defined FCLK_DIV value to the flash clock divide register (FCLKDIV). This is necessary before any commands can be issued to the FTM.

```

/***** (1) SET UP THE FLASH CLOCK DIVIDE REGISTER *****/
while (!FSTAT_CCIF) //Wait for FTM to be ready
{
}
FCLKDIV = FCLK_DIV; //Now write FCLKDIV before using the FTM.
if (FCLKDIV != (FCLK_DIV | 0x80)) //Ensure the value is written.
    ReportError(FDIV_NOT_SET); //Report an error code.
/*****

```

2. Use the debugger memory window to see the contents of sections 1 and 2 of the EEE RAM and buffer RAM respectively, before any data is modified.

```

/**** (2) CHECK BUFFER RAM CONTENTS FROM THE PREVIOUS RUN ****/
//Before any FTM commands are executed, check the debugger memory
//window and observe the contents of sections 1 (0xF00 to 0xFFFF)
//and 2 (0xE00 to 0xEFF) of the buffer RAM.
/*****

```

3. The “LaunchFlashCommand” function was written in this application note to accept parameters and execute FTM commands. For this step, a full partition is performed, which erases and initializes EEE RAM and EEE flash. Afterwards, the debugger memory window ([Figure 9](#)) shows all data in EEE RAM (section 1) in an erased state (0xFFFF). Adjacent sections of buffer RAM not managed by the FTM have seemingly random data values. Users should always check the FSTAT and FERSTAT registers for errors after completion of an FTM command.

```

/***** (3) PERFORM FULL PARTITION OF EEE RAM *****/
#ifdef FORCE_PARTITION_FOR_DEBUG //If defined, force EEE partition and eraser.

//Run LaunchFlashCommand to partition and erase the EEE in debug mode.
//Return the status of the FSTAT and FERSTAT Flash registers.
status = LaunchFlashCommand(2, FULL_PARTITION_D_FLASH, 0, DFPART, EEE_RAM, 0, 0, 0, 0, 0);

//Always check if any error bits are set.
ErrorCheck(status, accerr|fpviol|mgstat1|mgstat0, er serif|pgmerif|epviolif|ersvif1|ersvif0|dfdif|sfdif);
#endif
/*****

```

	Auto	Global
13FE00	F9 E3 DD 3E F3 8B EF F3	31 EC B1 35 E3 DB D3 76 ...>....1..5...v
13FE10	7C C4 35 D5 F9 9D A5 AC	75 DC 7F D5 A6 F2 6D BE .5.....u.....m.
13FE20	07 FF 31 DE 70 12 D8 47	11 DC A1 68 61 35 98 01 ..1.p..G...ha5..
13FE30	1E 80 61 3D E8 31 6C 44	A5 C4 48 1C 4E 84 1B DC ..a=.11D..H.N...
13FE40	7E 7F F6 8B 7E 47 B7 BA	3E 66 FF 0D 26 44 20 FF ~...~G..>f..&D .
13FE50	F9 FF AF FE 0D C5 D3 94	7B F6 A2 27 3B F9 01 F7{..'';...
13FE60	11 A9 40 97 77 5C 88 54	80 1B C4 16 72 31 1C 30 ..@.w\.T....r1.0
13FE70	81 28 20 47 46 FB 15 1E	A3 A4 17 8E 87 B8 64 94 .(GF.....d.
13FE80	4B 7F 9F D1 5E F3 6A CD	BF 7E 21 63 35 A4 7B BF K...^j..~!c5.{.
13FE90	F9 E3 EE F7 65 FA F1 0F	7F 1A 6F 7A EF E3 76 F3e.....oz..v.
13FEA0	1A 3B 34 0E B8 A0 41 49	21 84 64 81 55 91 C5 3E .;4...AI!.d.U..>
13FEB0	90 41 A0 83 42 F5 01 B3	1C 10 28 32 C3 99 00 11 .A..B.....(2....
13FEC0	97 59 C1 DF DE B5 FF 43	DF 64 6F BF 84 F7 EE 5C .Y.....C.do....\
13FED0	7F 3F 77 B5 F7 75 CF B1	14 DF C5 BD 2F AF E8 ED .?w.u...../...
13FEE0	32 8F 30 8C 4E DB 51 83	E4 83 35 04 90 4C 29 81 2.0.N.Q...5..L).
13FEF0	8D 58 A1 25 38 C4 0A CD	45 DC 9F 9E 74 09 45 D1 .X.%8...E...t.E.
13FFF0	FF FF FF FF FF FF FF FF	FF FF FF FF FF FF FF FF
13FFF10	FF FF FF FF FF FF FF FF	FF FF FF FF FF FF FF FF
13FFF20	FF FF FF FF FF FF FF FF	FF FF FF FF FF FF FF FF
13FFF30	FF FF FF FF FF FF FF FF	FF FF FF FF FF FF FF FF
13FFF40	FF FF FF FF FF FF FF FF	FF FF FF FF FF FF FF FF
13FFF50	FF FF FF FF FF FF FF FF	FF FF FF FF FF FF FF FF
13FFF60	FF FF FF FF FF FF FF FF	FF FF FF FF FF FF FF FF
13FFF70	FF FF FF FF FF FF FF FF	FF FF FF FF FF FF FF FF
13FFF80	FF FF FF FF FF FF FF FF	FF FF FF FF FF FF FF FF
13FFF90	FF FF FF FF FF FF FF FF	FF FF FF FF FF FF FF FF
13FFFA0	FF FF FF FF FF FF FF FF	FF FF FF FF FF FF FF FF
13FFFB0	FF FF FF FF FF FF FF FF	FF FF FF FF FF FF FF FF
13FFFC0	FF FF FF FF FF FF FF FF	FF FF FF FF FF FF FF FF
13FFFD0	FF FF FF FF FF FF FF FF	FF FF FF FF FF FF FF FF
13FFFE0	FF FF FF FF FF FF FF FF	FF FF FF FF FF FF FF FF
13FFFF0	FF FF FF FF FF FF FF FF	FF FF FF FF FF FF FF FF

Figure 9. Data in EEERAM after Erase

4. Check the partitioning by using a query command. The parameters can be read back from the FCCOBLO register. A match in the parameters ensures the EEE is partitioned as expected.

```

/*****(4)CHECK EEE PARTITIONING*****/
//Use flash command function to query the EEPROM partitioning.
//Return the status of the FSTAT and FERSTAT Flash registers.
status = LaunchFlashCommand(0 ,EEPROM_QUERY, 0, 0, 0, 0, 0, 0, 0, 0); //Check the EEE status

//Check if any error bits are set.
ErrorCheck(status, (accerr|fpviol|mgstat1|mgstat0), (er serif|pgmerif|epviolif|ersvif1|ersvif0|dfdif|sdfif));

FCCOBIX = 1; //Set CCOB index to get Data flash partition result.
dfPart = FCCOBLO; //Copy Data flash partition result.
FCCOBIX++; //Set CCOB index to get EEE RAM partition result.
erPart = FCCOBLO; //Copy EEE RAM partition result.

#ifdef FORCE_PARTITON_FOR_DEBUG //If defined, check that the FTM properly allocated
//and erased the EEE sectors in buffer RAM.

//Use query results to determine if D-Flash has been partitioned
//for EEPROM with erPart == EEE_RAM and dfPart == DFPART.
if (EEE_RAM > 0)

```

```

{
  if((erPart != EEE_RAM) || (dfPart != DFPART))
    ReportError(PARTITION_MISMATCH); //Full Partition was Unsuccessful
}
else if((erPart != -1) || (dfPart != -1))
{
  ReportError(PARTITION_MISMATCH); //EEE_RAM might be out of range (0-16)
}
#endif
/*****/

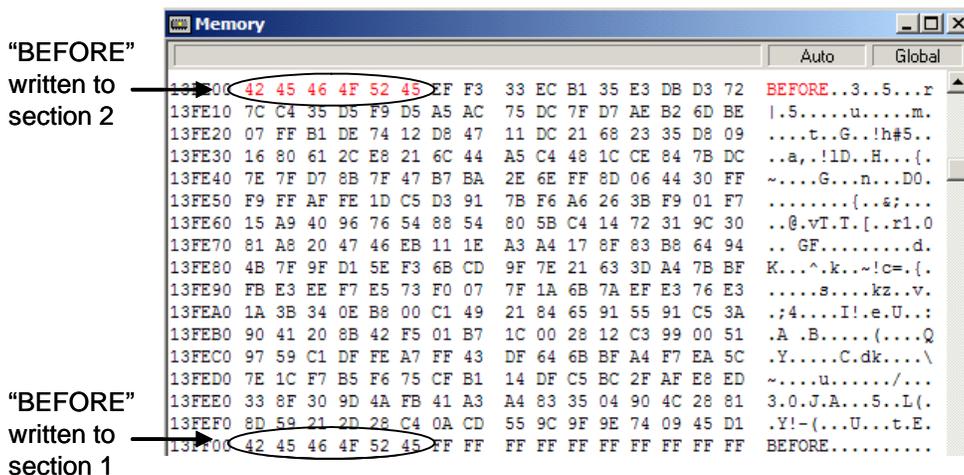
```

- This task illustrates that users can read and write freely to EEE RAM prior to enabling the EEE. The text string “BEFORE” is written at the beginning of the section. For comparison, the neighboring section of buffer RAM is also written with the same string. In this case, the data behaves as volatile data, and a power cycle at this point would result in a loss of all data in the buffer RAM as well as any data in the EEE RAM for which the FTM has not created a record. These strings will be checked again in later steps.

```

/****(5)WRITE PATTERN TO EEE SECTIONS BEFORE EEE ENABLED****/
//Now write the character pattern, "BEFORE", to the beginning of the
//1st and 2nd buffer RAM sections. The 1st 256byte section is partitioned
//as EEE RAM. The 2nd and remaining sections are general user RAM.
section1_ptr = copy_string(&before, section1_ptr);//Copy "BEFORE" to EEE RAM
section2_ptr = copy_string(&before, section2_ptr);//Copy "BEFORE" to user RAM
/*****/

```



- This step enables the EEE. Once enabled, the EEE recognizes that new data, from step 5, has been written to EEE RAM (section 1). The FTM stores records of this new EEE RAM data to the sectors of data flash partitioned as EEE flash. However, the same data written in the adjacent section of buffer RAM (section 2) is not backed up because this section was not partitioned as EEE RAM.

```

/*****(6)ENABLE WRITES OF EEE RECORDS*****/
//This enables the FTM to take any revised data written to the EEE
//partitioned section(s) of the buffer RAM and update the record(s)
//in the EEE partitioned section(s) of data Flash.
#ifdef ENABLE_EEE_RECORD_WRITING
  if(erPart > 0)

```

```

{
//Use flash command function to enable the FTM to manage EEE data and records.
//Return the status of the FSTAT and FERSTAT Flash registers.
status = LaunchFlashCommand(0 ,ENABLE_EEPROM_EMULATION, 0, 0, 0, 0, 0, 0, 0, 0);

//Check if any error bits are set.
ErrorCheck(status, (accerr|fpviol|mgstat1|mgstat0),
(er serif|pgmerif|epviolif|ersvif1|ersvif0|dfdif|sfdif));
}
/*****/

```

- The following instructions demonstrate that users can continue to read and write freely to the EEE RAM while EEE is enabled. However, the FTM may actively copy data written to the EEE RAM to store and maintain records in EEE Flash. “DURING” is the next string of text written, which is placed behind the previous string. The text strings should be observed in the debugger memory window, as shown in Figure 10.

```

/****(7)WRITE PATTERN TO EEE SECTORS WHILE EEE ENABLE****/
//Now write the character pattern, "DURING", after the character string,
//"BEFORE", which is at the beginning of the 1st and 2nd buffer RAM sections.
//The 1st 256byte section is partitioned as EEE RAM. The 2nd and remaining
//sections are general user RAM.
section1_ptr++; //Move to next character position
section2_ptr++; //Move to next character position
section1_ptr = copy_string(&during, section1_ptr);//Copy "DURING" to EEE RAM
section2_ptr = copy_string(&during, section2_ptr);//Copy "DURING" to user RAM
/****/

```

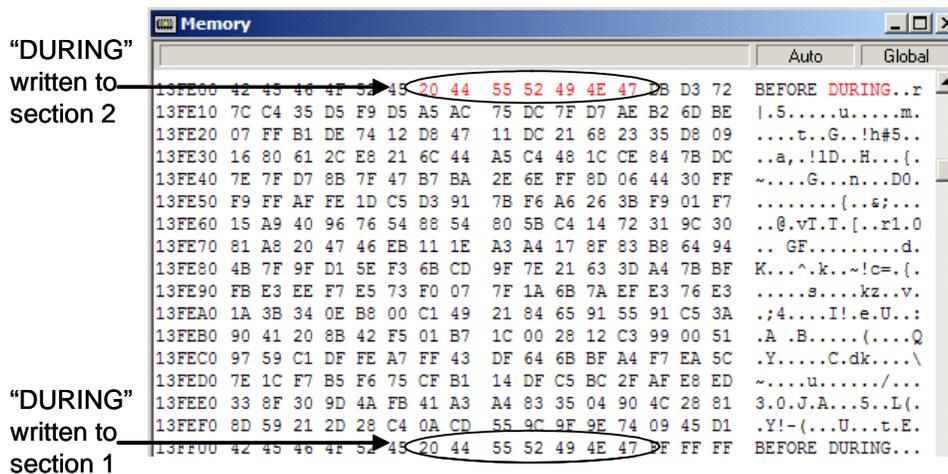


Figure 10. Results of Executing Step 7

- Next, the EEE will be disabled. However, before disabling the EEE, a status check is performed to ensure that the FTM is not currently busy and also that records for all modified EEE RAM data have been updated. The number of pending records to be stored or updated is tracked in the ETAG register. When ETAG reads 0, all records have been updated.

```

/*****(8)DISABLE WRITES OF EEE RECORDS*****/
if(erPart > 0)
{
//Wait for FTM to store new EEE RAM data into EEE Flash.

```

```

while(FSTAT_MGBUSY || ETAG)
{
    //Wait for FTM to finish writing data records to EEE Flash.
}

//Use to DISable the FTM from managing EEE data and records.
//Return the status of the FSTAT and FERSTAT Flash registers.
status = LaunchFlashCommand(0 ,DISABLE_EEPROM_EMULATION, 0, 0, 0, 0, 0, 0, 0, 0);

//Check if any error bits are set.
ErrorCheck(status, (accerr|fpviol|mgstat1|mgstat0), (er serif|pgmerif|epviolif|ersvif1|ersvif0|dfdif|sfdif));
}
#endif
/*****/

```

9. Write the last string (“AFTER”) to the EEE RAM and buffer RAM. Observe the string in the debugger. The memory window should resemble Figure 11.

```

/*****(9)WRITE PATTERN TO EEE SECTORS AFTER EEE DISABLE****/
//Now write the character pattern, "AFTER", after the character string,
//"DURING", which is at the beginning of the 1st and 2nd buffer RAM sections.
//The 1st 256byte section is partitioned as EEE RAM. The 2nd and remaining
//sections are general user RAM.
section1_ptr++; //Move to next character position
section2_ptr++; //Move to next character position
section1_ptr = copy_string(&after, section1_ptr);//Copy "AFTER" to EEE RAM
section2_ptr = copy_string(&after, section2_ptr);//Copy "AFTER" to user RAM
/*****/

```

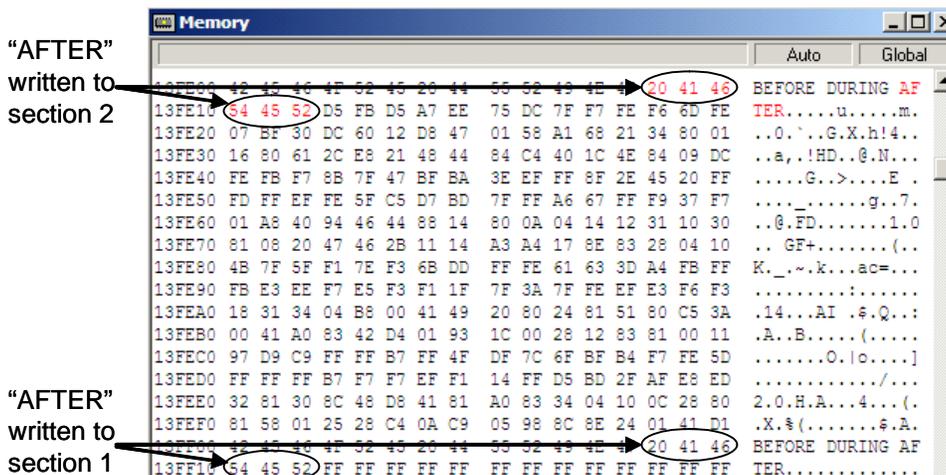


Figure 11. Results of Executing Step 9

10. This step does not require any execution of code, but observation of the memory window. Thus far, it has been demonstrated that as long as the CPU is active, data can be written in either buffer RAM or EEE RAM sections. The memory window should display these three text strings — “BEFORE”, “DURING”, and “AFTER” — in EEE RAM and the adjacent buffer RAM section. The following sub-steps illustrate buffer RAM and EEE RAM differences.

- a) Use the debugger to perform a reset. After reset, the FTM copies data from records stored in EEE flash back into EEE RAM. At this time, any attempt by the CPU to access EEE RAM before the FTM has completed the copy process will cause the CPU to be stalled until the FTM

has finished. The memory window should resemble Figure 12. Notice that the text string “AFTER” has disappeared from the EEE RAM. This is because no record of this string at this address was stored in EEE flash. Instead, the FTM returned all bytes of this address back to an erased state. Conversely, all three strings in the adjacent section of buffer RAM still remain despite the fact that the buffer RAM is volatile memory. This is because the MCU has not been power cycled.

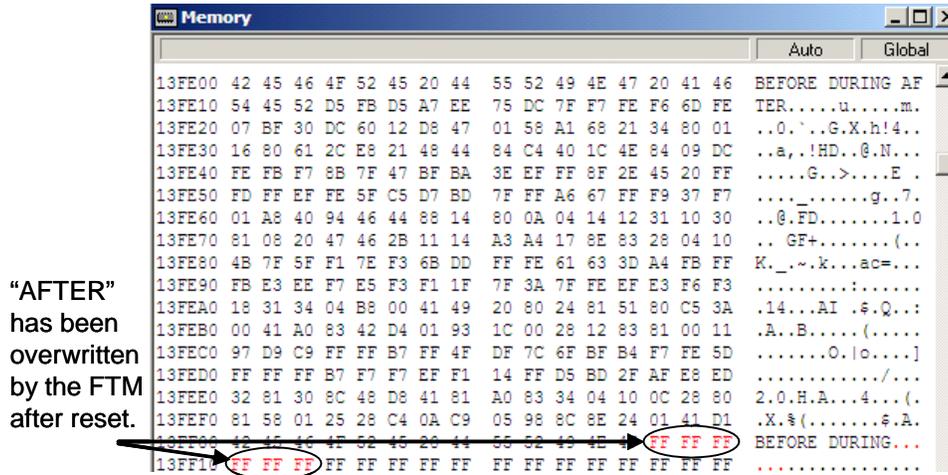
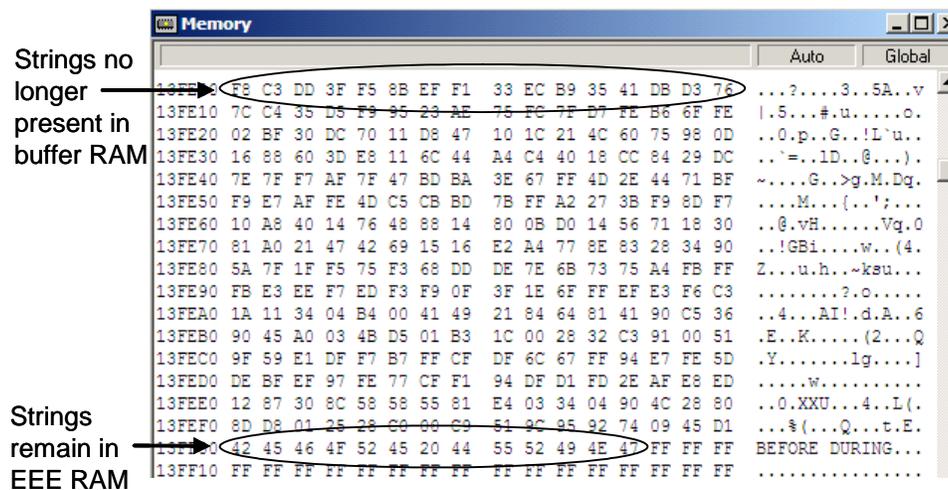


Figure 12. EEE RAM and Buffer RAM after Reset

- b) Now exit the debugger application. Power cycle the MCU to force all buffer RAM and EEE RAM to lose data. Reconnect to the MCU with the debugger; this can be done by reprogramming the same code back into the MCU.
- c) Without executing any code, observe the memory window and notice that all three strings have disappeared from the buffer RAM. The absence of these strings illustrates the volatility of the buffer RAM. The EEE RAM, however, still has the “BEFORE” and “DURING” strings since they were copied from EEE flash by the FTM. This feature allows the FTM to emulate EEPROM using flash and RAM resources.



7 Summary

The EEPROM feature of the S12X flash module is the newest enhancement allowing users the flexibility to configure the behavior of memory in the EEPROM region. After completing this example, users should understand the following points:

- The location of the EEPROM region and its physical subcomponents: buffer RAM and data flash
- The possible configurations of the EEPROM region
- The FTM command execution flow
- The necessity of always performing error checks after each FTM command execution
- How data behaves when written in buffer RAM and EEE RAM
 - before EEE is enabled
 - while EEE is enabled
 - after EEE is disabled
- That when EEE is partitioned, the CPU is stalled after a reset until the FTM has finished copying data from records in EEE flash back into EEE RAM

Although this application note highlights some of the characteristics of EEE, more details are available. See Freescale application note AN3490, “Overview of the MC9S12XE Emulated EEPROM,” for a broader overview of EEE.

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